

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6596562").PN.	US-PGPUB; USPAT	OR	OFF	2005/05/31 12:32
L3	9512	(dicing or sigulating) with (die or wafer or substrate)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:00
L4	4357	3 and pressure	US-PGPUB; USPAT	OR	ON	2005/05/31 12:33
L5	1132	4 and grooves	US-PGPUB; USPAT	OR	ON	2005/05/31 12:34
L6	269	5 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 13:30
L7	242	6 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:31
L8	46	grooves and (substrate or dice or wafer) and diaphram and pressure and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:10
L9	19	(singulating with dice) and grooves and (substrate or dice or wafer) and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:13
L10	177	(singulating with dice) and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:09
L11	158	10 not 9	US-PGPUB; USPAT	OR	ON	2005/05/31 12:52
L12	158	11 not 7	US-PGPUB; USPAT	OR	ON	2005/05/31 12:52
L13	577	(cutting with dice) and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:09
L14	103	13 and grooves	US-PGPUB; USPAT	OR	ON	2005/05/31 13:10
L15	96	14 not 9	US-PGPUB; USPAT	OR	ON	2005/05/31 13:10
L16	94	15 not 7	US-PGPUB; USPAT	OR	ON	2005/05/31 13:10
L17	94	16 not 12	US-PGPUB; USPAT	OR	ON	2005/05/31 13:10
L18	3	(singulating with dice) and grooves and (substrate or dice or wafer) and (bend or bow) and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:14
L19	73	(singulating with (substrate or wafer)) and (bend or bow) and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 13:15
L20	899	3 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:01

L21	793	20 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 14:01
L22	551	21 not 7	US-PGPUB; USPAT	OR	ON	2005/05/31 13:32
L24	267	22 and (flexible or elastic)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:01
L25	284	22 not 24	US-PGPUB; USPAT	OR	ON	2005/05/31 13:47
L26	10238	(dicing or singulating) with (die or wafer or substrate)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:30
L27	969	26 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:22
L28	856	27 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 14:22
L29	305	28 not 22	US-PGPUB; USPAT	OR	ON	2005/05/31 14:01
L30	198	29 and (flexible or elastic)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:09
L31	107	29 not 30	US-PGPUB; USPAT	OR	ON	2005/05/31 14:09
L32	872	(dicing or singulating) with (dice)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:24
L33	94	32 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:25
L34	81	33 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 14:25
L35	621	(cutting) with (dice)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:27
L36	49	35 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:31
L37	45	36 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 14:27
L38	22506	(cutting) with (die)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:27
L39	3099	38 and ((apply or applying) with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 15:09
L40	2949	39 and @ad<"20031027"	US-PGPUB; USPAT	OR	ON	2005/05/31 14:52
L41	527	40 and (flexibale or bow or elastic)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:33
L42	527	41 not 25	US-PGPUB; USPAT	OR	ON	2005/05/31 14:29
L43	5889	(dicing or singulating) with (die or dice or wafer or substrate)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:33

L44	37	43 and ((apply or applying) with pressure)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:33
L45	38338	(cutting) with (die or dice or wafer or substrate)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:33
L46	1517	45 and ((apply or applying) with pressure)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:33
L47	129	46 and (flexibale or bow or elastic)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:33
L48	1819	dicing and substrate and (flexible) and pressure	US-PGPUB; USPAT	OR	ON	2005/05/31 15:01
L49	1253	48 and applying	US-PGPUB; USPAT	OR	ON	2005/05/31 14:53
L50	444	48 and (applying with pressure)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:53
L51	144	50 and (bend or bow)	US-PGPUB; USPAT	OR	ON	2005/05/31 14:53
L52	19	dicing and substrate and (flexible) and pressure	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:01
L54	0	(oi adj fong adj chin) or (yew adj wee adj cheong) or (weng adj khoon adj mong)	US-PGPUB; USPAT	OR	ON	2005/05/31 15:12
L56	0	(oi adj fong adj chin) or (yew adj wee adj cheong) or (weng adj khoon adj mong)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:12

DERWENT-ACC-NO: 2000-372436

DERWENT-WEEK: 200032

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TITLE: Wafer dicing for use during semiconductor integrated circuit manufacture, involves adjoining spacer to cleavage plane of wafer and applying pressure simultaneously to wafer and spacer so that wafer breaks to pieces

----- KWIC -----

Basic Abstract Text - ABTX (2):

USE - For dicing semiconductor wafer that mounts semiconductor chip e.g. LED chip for semiconductor integrated circuit manufacture.

Title - TIX (1):

Wafer dicing for use during semiconductor integrated circuit manufacture, involves adjoining spacer to cleavage plane of wafer and applying pressure simultaneously to wafer and spacer so that wafer breaks to pieces

Standard Title Terms - TTX (1):

WAFER DICE SEMICONDUCTOR INTEGRATE CIRCUIT MANUFACTURE  
ADJOIN SPACE CLEAVE  
PLANE WAFER APPLY PRESSURE SIMULTANEOUS WAFER SPACE SO  
WAFER BREAK PIECE

DERWENT-ACC-NO: 2004-812350

DERWENT-WEEK: 200517

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TITLE: Cutting of glass sheet or PDP substrate comprises forming linear groove in glass sheet along programmed cutting line that is set for glass sheet, and applying local pressure to end of groove

----- KWIC -----

Basic Abstract Text - ABTX (1):

NOVELTY - Glass sheet is cut by forming a linear groove in glass sheet along a programmed cutting line that is set for the glass sheet, and applying local pressure to an end of the groove.

Basic Abstract Text - ABTX (4):

(B) a cutting apparatus for cutting a glass sheet comprising elastic plate arranged at an end of a programmed cutting line of a glass sheet for dissipating pressure, pressure absorber arranged on the rear surface of the glass sheet opposing the end of the cutting line, and pressurizing mechanism (6) for applying pressure to the elastic plate.

Basic Abstract Text - ABTX (5):

USE - For cutting a glass sheet or PDP substrate.

Basic Abstract Text - ABTX (7):

DESCRIPTION OF DRAWING(S) - The figure is front view showing another part of the cutting apparatus for cutting a PDP substrate.

Basic Abstract Text - ABTX (16):

Elastic plates 15, 20

Title - TIX (1):

Cutting of glass sheet or PDP substrate comprises forming linear groove in glass sheet along programmed cutting line that is set for glass sheet, and applying local pressure to end of groove

Standard Title Terms - TTX (1):

CUT GLASS SHEET SUBSTRATE COMPRISE FORMING LINEAR GROOVE  
GLASS SHEET  
PROGRAM CUT LINE SET GLASS SHEET APPLY LOCAL PRESSURE END  
GROOVE